



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#4a
7.21.99
mH

Applicant(s): Mostafazadeh, Shahram; Smith, Joseph O.
Assignee: National Semiconductor Corp.
Title: LEAD FRAME DESIGN FOR INCREASED CHIP PINOUT
Serial No.: 09/054,380 Filed: 04/02/98
Examiner: H. Duong Group Art Unit: 2822
Docket No.: NS-3856 US

San Jose, California
July 8, 1999

BOX
ASSISTANT COMMISSIONER FOR PATENTS
Washington, D. C. 20231

AMENDMENT

Dear Sir:

In response to the Office Action of January 21, 1999, Applicants amend the above-referenced patent application as follows:

IN THE CLAIMS

Please cancel Claim 10.

In Claim 2, at line 1, please delete "1" and substitute --11--.

Please amend Claims 1, 5 and 9 as follows:

1. (amended) [In an] An integrated circuit package comprising,

(a) a lead frame comprising:

a die attach platform; and

RECEIVED

JUL 19 1999

TECHNOLOGY CENTER 2800

LAW OFFICES OF
SKJERVEN, MORRILL,
MacPHERSON, FRANKLIN
& FRIEL LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979

532211 v1

- 1 -

SER. NO. 09/054,380